

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>I-MIN TSENG</td> <td>12/04/2013</td> </tr> <tr> <td>JINN-JONG WONG</td> <td>12/04/2013</td> </tr> <tr> <td>WEN-CHUAN HSU</td> <td>12/04/2013</td> </tr> <tr> <td>HUA-TANG YUE</td> <td>12/04/2013</td> </tr> </tbody> </table>		Name	Execution Date	I-MIN TSENG	12/04/2013	JINN-JONG WONG	12/04/2013	WEN-CHUAN HSU	12/04/2013	HUA-TANG YUE	12/04/2013
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CORRESPONDENCE DATA											
<p>Fax Number: (703)621-7155</p> <p>Phone: 703-621-7140</p> <p>Email: MAILROOM@MG-IP.COM</p> <p><i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i></p> <p>Correspondent Name: MUNCY, GEISSLER, OLDS & LOWE, PLLC</p> <p>Address Line 1: 4000 LEGATO ROAD</p> <p>Address Line 2: SUITE 310</p> <p>Address Line 4: FAIRFAX, VIRGINIA 22033</p>											
ATTORNEY DOCKET NUMBER:	0941/2785PUS2										
NAME OF SUBMITTER:	JOE MCKINNEY MUNCY										

Signature:	/Joe McKinney Muncy/
Date:	12/18/2013
Total Attachments: 1 source=2013-12-18-executedAssignment-AsFiled#page1.tif	

ASSIGNMENT

WHEREAS, I-Min TSENG, Jinn-Jong WONG, Wen-Chuan HSU and Hua-Tang YUE hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: Method for preparing phenol-formaldehyde resins, resin materials and method for preparing resin molding materials

Filed: December 11, 2013

Serial No. 14/103,415


Executed on: December 4, 2013


WHEREAS, Industrial Technology Research Institute of No. 195, Sec. 4, Chung Hsing Rd., Chung, Hsinchu 31040, Taiwan, R. O. C. hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;


NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

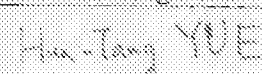
Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Full name of sole or first inventor: <u>I-Min TSENG</u>	
Inventor's signature: 	Date: <u>2013.12.4</u>

Full name of second inventor: <u>Jinn-Jong WONG</u>	
Inventor's signature: 	Date: <u>2013.12.4</u>

Full name of third inventor: <u>Wen-Chuan HSU</u>	
Inventor's signature: 	Date: <u>2013.12.4</u>

Full name of third inventor: <u>Hua-Tang YUE</u>	
Inventor's signature: 	Date: <u>2013.12.4</u>